

Amendments to the Claims

The listing of claims will replace the previous version, and the listing of claims:

Listing of Claims

1. (currently amended) A micro power converter with multiple outputs, comprising:

a semiconductor substrate having a semiconductor integrated circuit,

a plurality of thin film magnetic induction components electrically connected to the semiconductor integrated circuit ~~and arranged to be spaced apart from each other with a gap therebetween,~~ each of said thin film magnetic induction components comprising a magnetic insulation substrate and a coil conductor formed on the magnetic insulation substrate, one magnetic insulation substrate forming one thin film magnetic induction component with the coil conductor thereon being spaced with a gap from another magnetic insulation substrate forming another thin film magnetic induction component with the coil conductor thereon, and

a capacitor electrically connected to the semiconductor integrated circuit.

2. (original) A micro power converter according to claim 1, further comprising a magnetic isolation layer disposed in the gap between the magnetic insulation substrates for magnetically isolating the thin film magnetic induction components.

3. (previously presented) A micro power converter according to claim 1, wherein each of said thin film magnetic induction components further includes a plurality of connection terminals formed at a peripheral portion of said one magnetic insulation substrate, said plurality of the thin film magnetic induction

components being arranged with the gap and attached at the plurality of the connection terminals.

4. (original) A micro power converter according to claim 1, wherein said plurality of the magnetic insulation substrates is formed of a ferrite substrate.

5. (original) A micro power converter according to claim 2, wherein said magnetic isolation layer is formed of a non-magnetic material.

6. (original) A micro power converter according to claim 5, wherein said non-magnetic material is a resin material.

7. (original) A micro power converter according to claim 5, wherein said non-magnetic material is a ceramic material.

8. (original) A micro power converter according to claim 3, wherein said plurality of the connection terminals is formed on each of the plurality of the magnetic insulation substrates at same planar positions, said plurality of the connection terminals connected to two ends of each coil inductor and located on one magnetic insulation substrate being located at planar positions different from those of another magnetic insulation substrate.

9. (original) A micro power converter according to claim 8, wherein one of said plurality of the connection terminals formed on one magnetic insulation substrate faces another magnetic insulation substrate, and has a height greater than that of the coil conductor formed on the one magnetic insulation substrate.

10. (original) A micro power converter according to claim 3, wherein said plurality of the connection terminals includes a first

terminal formed on a front surface of one magnetic insulation substrate and a second terminal formed on a rear surface of the one magnetic insulation substrate, said first terminal being electrically connected to the second terminal through a hole formed in the one magnetic insulation substrate.

11. (original) A micro power converter according to claim 10, wherein said semiconductor substrate is electrically connected to the first terminal.

12. (original) A micro power converter according to claim 10, wherein said capacitor is electrically connected to the first terminal.

13. (previously presented, withdrawn) A micro power converter according to claim 1, wherein said coil conductor comprises upper and lower conductor portions formed on and under the magnetic insulation substrate, and connecting conductors for connecting the upper and lower conductor portions to form one conductor.

14. (previously presented, withdrawn) A micro power converter according to claim 13, wherein said magnetic insulation substrate includes holes spaced apart from each other, in which said connecting conductors are disposed, so that the upper and lower conductor portions and the connecting conductors surround a part of the magnetic insulation substrate.

15. (previously presented, new) A micro power converter according to claim 14, wherein said upper and lower conductor portions have linear portions between the connecting conductors.